

Technical Data

Application :

The high thermal conductivity material made by Gofang offers you an effective solution to the most difficult heat problem in electronic field. With high thermal conductivity adhesive based on Aluminum or copper, it rapidly transfers the heating from components like LED or IC chip to the back of the substrate, then go outside through further heat dissipation modules, so such LEDs or IC chips working does not shut down or decline under too high heating conditions. It also accounts for a remarkable influence on high-power LED lighting, Back-light Unit, high power Supply or IC packaging.

Feature :

- * Low thermal resistance.
- * Integral aluminum or copper base plate for heat dissipation.
- * High performance in thermal shock and thermal cycle.
- * Simplify to design circuit layout on one or double side copper foil.
- * Use standard PCB fabrication techniques and processes.

Typical properties :

PROPERTY	GF-TP-H60	GF-TP-H120	TEST
Dielectric thickness (μm)	60 ± 5	120 ± 5	Gofang test
Size (mm) @ 100M	527	527	Gofang test
Peel strength (kgf/cm)	≥ 2.0	≥ 2.0	IPC-TM-650 2.4.9
Solder dip test (300°C 30sec)	Pass	Pass	IPC-TM-650 2.4.13
Chemical resistance	Pass	Pass	IPC-TM-650 2.3.2
Surface resistance (ohm)	$> E+14$	$> E+14$	ASTM-D247
Volume resistance (ohm · cm)	$> E+15$	$> E+15$	ASTM-D257
Breakdown voltage (ACV/mil)	900	900	IPC-TM6502.5.6
Glass transition temp. (°C)	120	120	DSC
Thermal conductivity (W/m.k)	1.8	1.8	ASTM-D5470
Shelf life (month)	2	2	Gofang test

In the future, we will keep continually developing products and improving competitive advantages to meet customers' requirements, providing satisfied after-service. If interested, just contact us.

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